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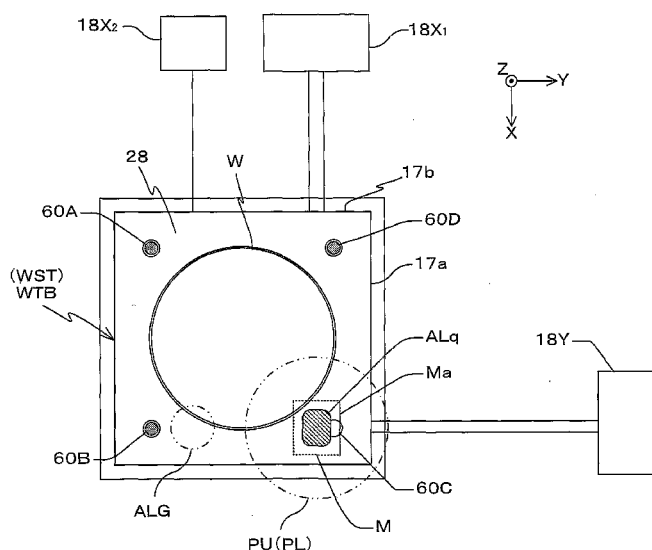
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(54) Title: EXPOSURE APPARATUS, EXPOSURE METHOD, AND DEVICE MANUFACTURING METHOD

Fig. 3



(57) Abstract: In an exposure apparatus of a liquid immersion exposure method, there is a case when a wafer table (WTB) holding a wafer (W) moves, a liquid immersion area (ALq) formed by liquid supplied in a space between the wafer table (WTB) and a projection optical system (PL) passes over a head (60A to 60D) mounted on the wafer table (WTB). Therefore, for a head (60C) over which the liquid immersion area (ALq) has passed, the residual presence of the liquid is detected based on an amount of light of a reflected light received by the light receiving element which receives the reflected light from the wafer table surface. And, of a plurality of heads, positional information of the wafer table (WTB) is measured, based on measurement values of a head that had no liquid remaining in the detection.